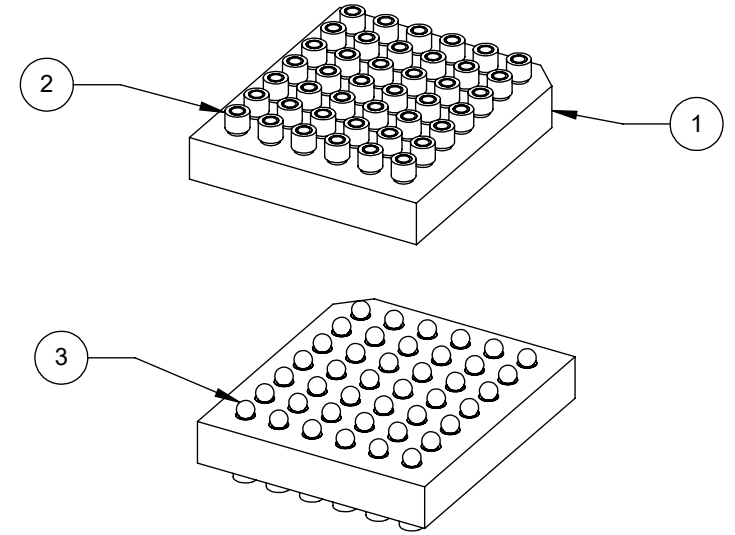
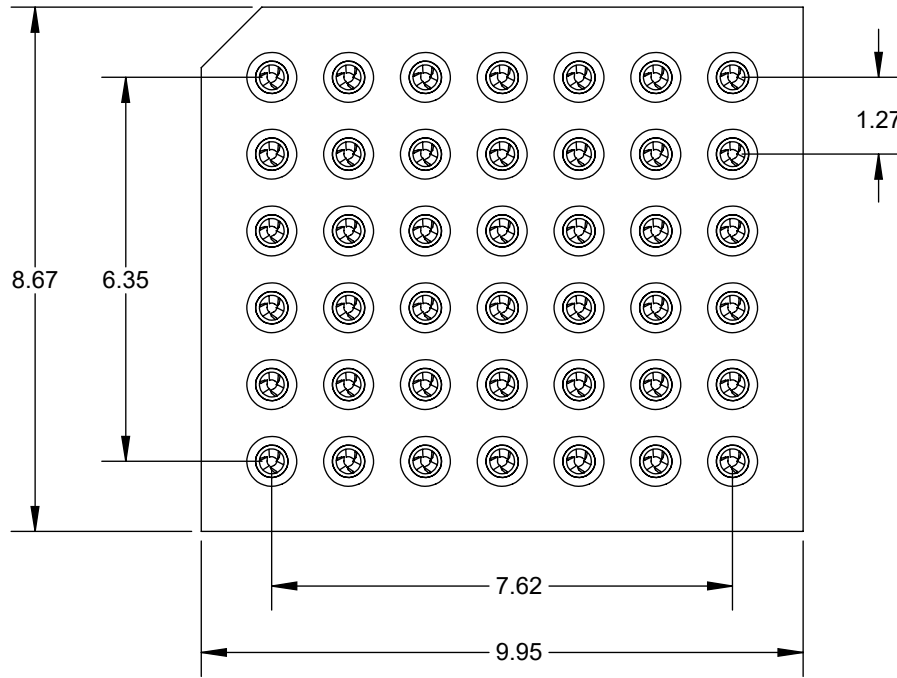
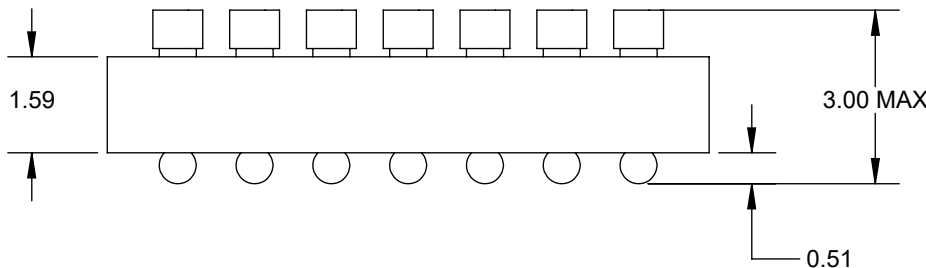


# U.S. Patent No. 8,091,222 B2



ITEM NO.	DESCRIPTION
1	High Temp Substrate
2	Gold plated socket pin
3	Solder ball, $\phi$ 0.024", Sn63 Pb37




**NOTE: Packaged in 24mm carrier tape**

**Description: Female foot for 6x7 array 1.27mm pitch**

Primary dimension units are millimeters, Secondary dimension units are [inches].

**Tolerances:** Hole diameters  $\pm 0.03\text{mm}$  [ $\pm 0.001"$ ], Pitches (from true position)  $\pm 0.025\text{mm}$  [ $\pm 0.001"$ ], substrate thickness tolerance  $\pm 10\%$ , all other tolerances  $\pm 0.13\text{mm}$  [ $\pm 0.005"$ ] unless stated otherwise. Materials and specifications are subject to change without notice.

 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: N/A	STATUS: Released ENG: B. Schatz FILE: SF-BGA42A-B-32 Dwg	SHEET: 1 OF 1 SCALE: 8:1 DATE: 09/18/2015	REV. A
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